ABSTRACT

A heat-resistant resin varnish characterized by comprising a polyamideimide resin whose terminal isocyanate group is blocked with a blocking agent and a polyamic acid, which is freed from viscosity increase even without employing any complicated step such as heating or cooling and which is easily applicable to a substrate and can form, through curing, films having excellent strength and elongation (toughness) equivalent to those of polyimide resin; heat-resistant resin films which are made of a heat-resistant resin formed by baking the varnish and have excellent toughness; heat-resistant composites having the heat-resistant resin films; and insulated wire which is covered with an insulating coating film made from the varnish through curing and having excellent toughness and which can be easily manufactured at a low cost.